HEIDELBERG INSTRUMENTS

MLA 300

THE MASKLESS ALIGNER FOR VOLUME PRODUCTION

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The MLA 300 features our powerful Maskless Aligner technology that has been specifically adapted to the requirements of high-throughput production applications: You can now employ the unmatched flexibility of maskless lithography in an industrial setting, on wafers with sizes up to 300 x 300 mm^2. Lithography no longer depends on a fixed mask, but can dynamically adapt to surface and process variations from previous fabrication steps.

A MASKLESS ALIGNER FOR INDUSTRY

The MLA 300 is based on the Heidelberg Instruments Maskless Lithography technology, which has become a standard in Research & Development applications, rapid prototyping, and low- to mid-volume production. The MLA 300 is the industrial production version of the Maskless Aligner, with outstanding specifications: It achieves high resolutions of 2 µm lines and spaces at the high throughput and high availability expected in production. It features full automation with wafer robot and load ports, and software specifically designed for the production environment to offer a simplified automated workflow.

THE MASKLESS TECHNOLOGY

The Maskless Aligner technology uses a Spatial Light Modulator which essentially acts like a dynamic mask. It offers the flexibility to structure the most challenging substrates, allowing per-die pattern corrections (e.g. to react to distortions or process variations), and employs a real-time autofocus to follow substrate warp or corrugations. The non-contact exposure gives the system an unmatched durability and reliability. The overheads and expense associated with the procurement of masks, and their handling, cleaning, and storage are also eliminated.

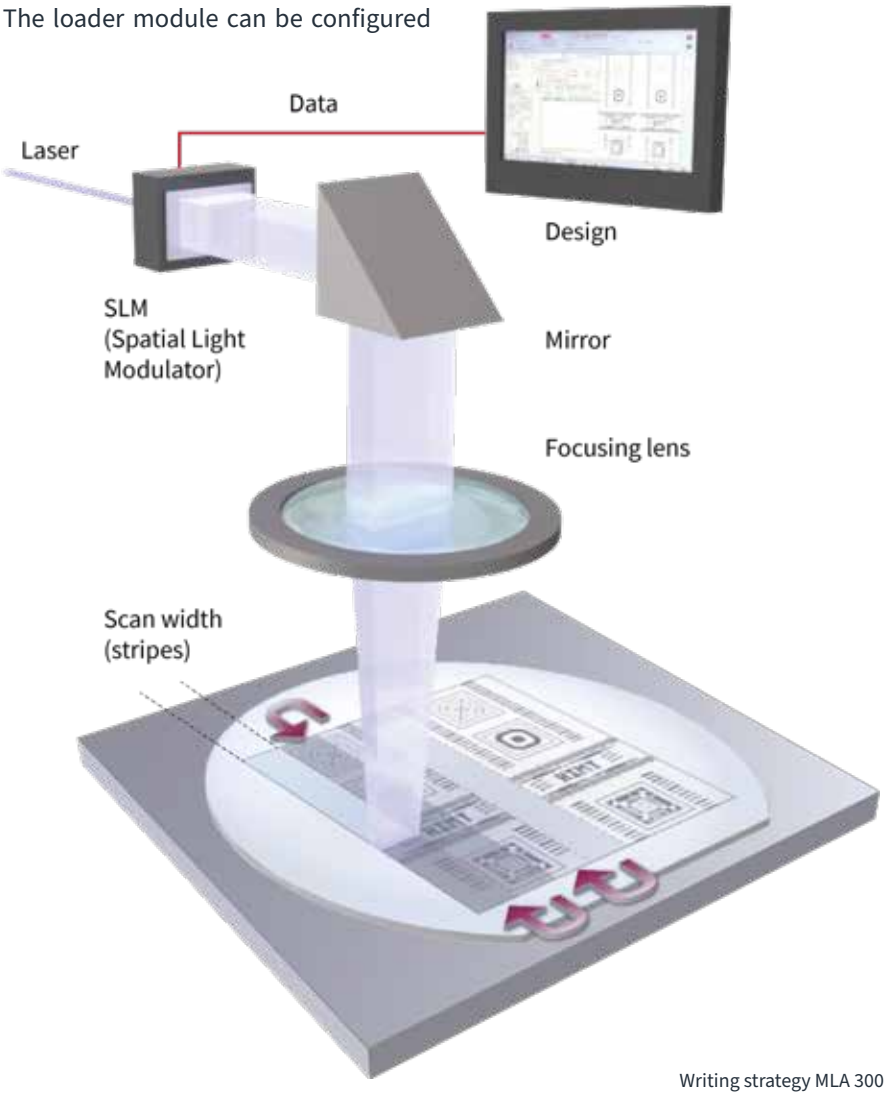
The system is designed for low total cost of ownership with its long-life diode laser and no consumables requirements. The positioning system is based on a frictionless air-bearing table, which offers high speed and high-accuracy motion, while simultaneously optimizing durability and lifetime.

APPLICATIONS

The MLA 300 excels in application areas such as the production of sensors, sensor ICs, MEMS devices, discrete electronic components, analog and digital ICs, ASICs, Power electronics, OLED displays, as well as for advanced packaging applications.

MAXIMUM FLEXIBILITY

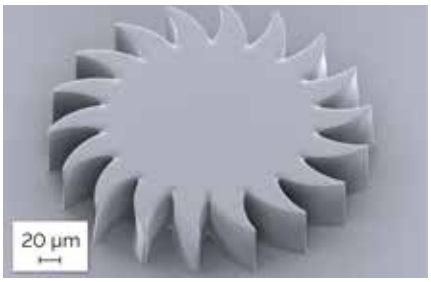
The novel modular concept allows maximum flexibility for the MLA300, which can thus be tailored to the production task and facility requirements. The loader module can be configured to interface to existing substrate carrier or FOUP systems and ensures seamless integration to the production line. The fully integrated exposure modules are available for a selection of wavelengths (375 nm or 405 nm) and with different resolution options. Multiple exposure modules can be mounted in the MLA 300, either operating a single module optimized for the product and resist (wavelength, resolution or throughput), or operating multiple identical modules simultaneously for further increased throughput.



Writing strategy MLA 300

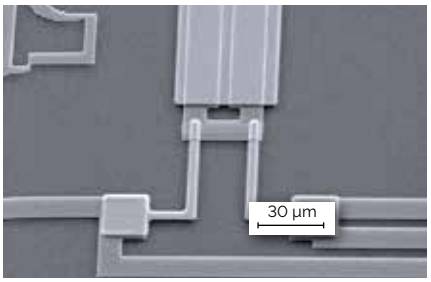
MASKLESS LITHOGRAPHY IN INDUSTRIAL PRODUCTION: APPLICATION AREAS

MEMS



MEMS processes integrate standard microchip technologies with electromechanical components of a diverse range of sizes and materials. Stresses and stress-induced deformations need to be managed carefully to yield correct device properties. The Maskless Aligner technology is ideally suited to make on the fly corrections to the design if required.

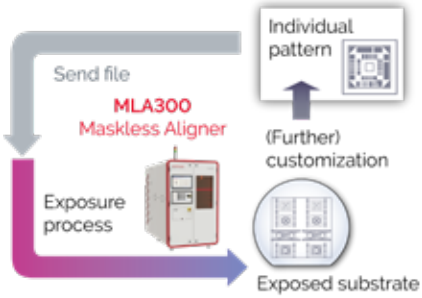
SENSORS



Maskless lithography provides extreme overlay accuracy. The production of SQUID devices may involve as many 18 layers. The alignment is completed automatically with the Maskless Aligner technology (demonstrated here by the MLA 150).

SQUID image courtesy of the Kirchhoff Institute for Physics (KIP), Heidelberg University

CUSTOMIZED PRODUCTS



The benefit of Maskless Lithography is the inherent rapid turnaround and adaptation of the exposed patterns. Modifications for customized products no longer entail production and maintenance of an expensive mask set. Switching between product types is seamless, and does not require intervention to change masks.

WARPED SUBSTRATES

Structuring warped substrates is challenging, as shape and distortions vary with applied forces. Maskless lithography offers the unique option of exposing the substrates with warpage-dependent pre-distortions, to maximise yield. Electronic components are often produced on substrate materials such as ceramics which are selected for their robustness or thermal properties rather than surface quality. The Maskless Aligner technology flexibly follows surface warp and corrugations, increasing uniformity and yield. Process variations can also be compensated for dynamically by adjusting the exposed pattern.

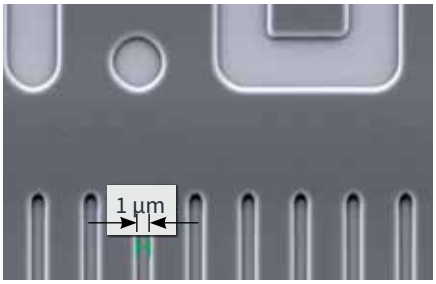
Fan-out wafer-level technology helps to achieve a high I/O-density and allows the flexible, heterogeneous integration of multiple chips. Challenges include varied chip heights and warped substrates. These can be solved by the benefits provided by Maskless Lithography: A special wafer handling system, customizable vacuum chucks, and a large autofocus compensation range.

MLA 300 HIGHLIGHTS

- High throughput
- Dynamic distortion correction
- Handling of challenging substrates (warpage!)
- Contactless exposure
- High precision and overlay accuracy
- Flexible pattern adaptations and alterations
- Individual labeling
- Confidentiality
- Quick time to market
- Quick turnaround time
- Low cost of ownership

RESOLUTION OPTIONS

We are currently in the evaluation stage of two additional resolution options for the MLA 300. The 1 µm high-resolution write mode allows even finer features to be resolved. The lower-resolution 4 µm write mode offers significantly higher throughput if maximum resolution is not required.



The MLA 300 is available in a variety of configurations with or without different types of automatic loaders. Each system will be customized exactly to suit your applications and requirements.

MLA 300

SYSTEM SPECIFICATIONS

Writing performance	
Minimum lines and spaces [µm]	2
Minimum feature size [µm]	1.5
CD uniformity [3σ, nm]	200
Edge roughness [3σ, nm]	80
Stitching [3σ, nm]	120
2nd layer alignment [3σ, nm]	500
Backside alignment [3σ, nm]	1000
Exposure time per module (100 x 100 mm^2 at 50 mJ/cm^2 and 405 nm laser wavelength)	2.6 min
Maximum write speed with one module at 405 nm laser wavelength	5000 mm^2/min
	Specifications of additional write modes to be confirmed
System features	
Light source	Laser wavelength: 375 nm and 405 nm High power diode laser with long life-time
Maximum substrate size	300 x 300 mm^2
Maximum exposure area	300 x 300 mm^2
Substrate thickness	0.1 - 10 mm
Modular environmental chamber	Temperature stability ± 0.1°C
Real-time autofocus	Optical and/or pneumatic autofocus
Autofocus dynamic range	Up to 150 µm
Alignment	Advanced alignment; backside alignment optional
Automation	Automatic wafer handling and pre-alignment
System dimensions (excluding loader)	
Height × width × depth	1980 mm x 1200 mm x 2310 mm
Weight	2600 kg
Installation requirements	
Electrical	400 VAC, 50/60 Hz, 16 A
Compressed air	7 - 10 bar

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